



Test Research, Inc. (TRI), ein führender Test- und Prüfsystemen Anbieter für die Elektronikfertigungsindustrie, kehrt in der productronica 2015 mit einem leistungsfähigen und kosteneffizienten Produktpalette, die eine vollständige Palette von Lösungen für die Inspektion und Baugruppenprüfung umfasst. Wir freuen uns darauf, Sie zu einer Live-Demo der folgenden Systeme an unseren Stand in **Halle A2 Stand 320 auf Messe München | 10.-13. November** zu begrüßen.

AOI



NEW!

TR7700Q 3D AOI

- Stop&Go Inline 3D AOI
- Quad DLP 3D Technology
- Micro Component Ready (0250125mm)
- 20 mm Adaptive 3D Range

TR7500 SIII 3D 3D AOI

- Leading 3D AOI Speed
- Total 2D + 3D Coverage
- 5 Color Cameras
- Automotive + HDI Applications



TR7700 SII Plus Hybrid AOI

- Unique Hybrid AOI
- Stop& Go + Dynamic Imaging for Top Speed on any PCB
- Foreign Mat. Inspection



ICT

NEW!

TR5001 SII INLINE ICT

- Multi-core Parallel ICT
- SafeDrive Per-pin Protection
- Fast Easy Programming
- New Software UI!



TR5001T SII TINY ICT

- Most Powerful TINY ICT
- Parallel Testing
- Fast Programming
- New Software UI!



SPI

NEW!

TR7007QI 3D SPI

- Stop&Go Inline 3D SPI
- Quad DLP 3D Technology
- Ultra-High Accuracy
- SmartWarp Compensation



TR7007 SII Plus 3D SPI

- Ultimate 3D SPI Solution
- Industry Leading Inspection Speed
- High Precision and Accuracy
- Closed Loop Integration



AXI

TR7600 SII with CT 3D AXI

- High performance Inline 3D X-ray
- Planar CT Upgrade
- Up to 900x460 mm PCB
- BGA, LGA, PoP, PTH, QFN inspection

NEW!



YMS 4.0

- Defect Image Analysis and Reporting
- Intelligent Line Management Solution
- Integrated SPI, AOI, AXI & ICT Dashboard
- Remote SPC Analysis and Control
- Industry 4.0 Quality Improvement

